



<b>LIST OF REFERENCES CITED BY APPLICANT</b> <i>(Use several sheets if necessary)</i>	ATTY. DOCKET NO.:	APPLICATION SERIAL NO.:
	4717-8600	10/726, 039
	APPLICANT: Bruno GHYSELEN et al.	
	FILING DATE:	GROUP:
	December 1, 2003	2812

## U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
Dle	AA	5,882,987 ✓	3/1999	Srikrishnan	438	458	
	AB	6,284,628 B1	9/2001	Kuwahara et al.	438	459	
	AC	6,306,729 B1	10/2001	Sakaguchi et al..	438	458	
	AD	6,326,279 B1	12/2001	Kakizaki et al.	438	406	
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Dle	AF	2002/0072130 A1	6/2002	Cheng et al.	438	10	

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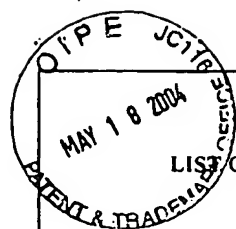
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
Dle	AG	EP 0 955 671 A1	11/1999	Europe			X	
	AH	EP 1 039 513 A2	9/2000	Europe			X	
	AI	EP 0 926 709 A2	6/1999	Europe			X	
	AJ	WO 01/11930 A2	2/2001	PCT			X	

## OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)

Dle	AK	L. J. Huang et al, "SiGe-on-insulator prepared by wafer bonding and layer transfer for high-performance field-effect transistors", Applied Physics Letters, Vol. 78, No. 9, pp. 1267-1269 (2001)
Dle	AL	Q. Y. Tong et al "Extracts of "Semi-conductor on wafer bonding", Science and Technology, Interscience Technology, Wiley Interscience publication, Johnson Wiley & Sons, Inc.
	AM	

EXAMINER  Dle	DATE CONSIDERED  4/2005
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\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.



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*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
<i>De</i>	AA	6,375,738	4/2002	Sato	117	89	
	AB						
	AC						
	AD						
	AE						
	AF						

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		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
<i>De</i>	AG	EP 1006 567 A2	6/2000	Europe			X	
	AH	EP 0 849 788 A2		Europe			X	
	AI	WO 99/53539	10/1999	PCT			X	
	AJ							

**OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)**

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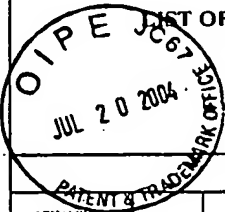
EXAMINER

*De*

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*4/2005*

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*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE	
Dle	AA	2001/0029072 A1	10/2001	Kuwahara et al.	438	151	
	AB	2001/0003269 A1	6/2001	Wu et al.	117	94	
	AC	2002/0068419 A1	6/2002	Sakaguchi et al.	438	458	
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DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION			
					YES	NO		
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AJ								

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<b>EXAMINER</b>  <span style="font-size: 2em;">Dle</span>	<b>DATE CONSIDERED</b>  <span style="font-size: 1.5em;">4/2005</span>
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